

Each column has 64 groups of 5 connected terminals with 0.1 inch grid spacing.

Specifications:

Length: 6.77"Width: 1.54"Height: 0.39"Tie points: 640

Resistance: <10mΩ (Ø0.6mm lead @ 1KHz)
Capacitance: <10pF (Ø0.6mm lead @ 1KHz)
Continuous working temperature: 50°C max.

• Insulation: >10T Ω (500VDC for 1 minute)

Contact current: 3A (ø0.6mm lead)

• Wire size acceptability: ø0.3mm~ø0.8mm

• HI-POT test: 1500VDC for 1 minute

• Breakdown current: 30mA

 Note: do not use high voltage on the bread board (AC>50V, CDC>75V)

• External body material: ABS polymer (90°C max.)

• Internal contact material: silver & nickel alloy

 Snap lock design allows easy combination with each other for greater design flexibility

383-K64